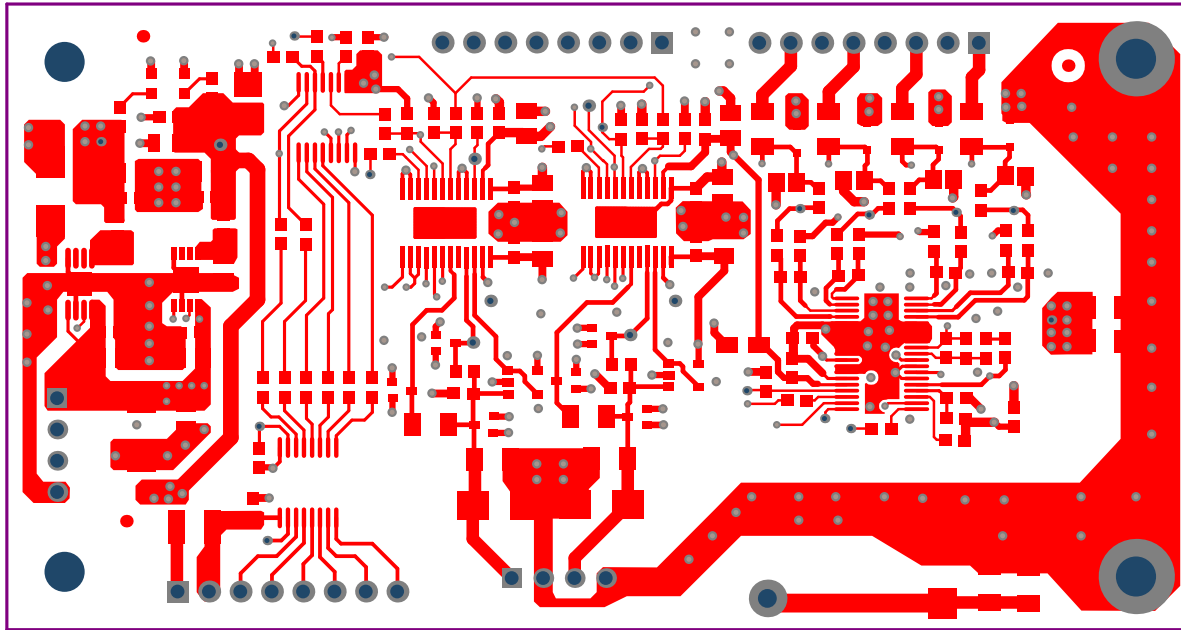
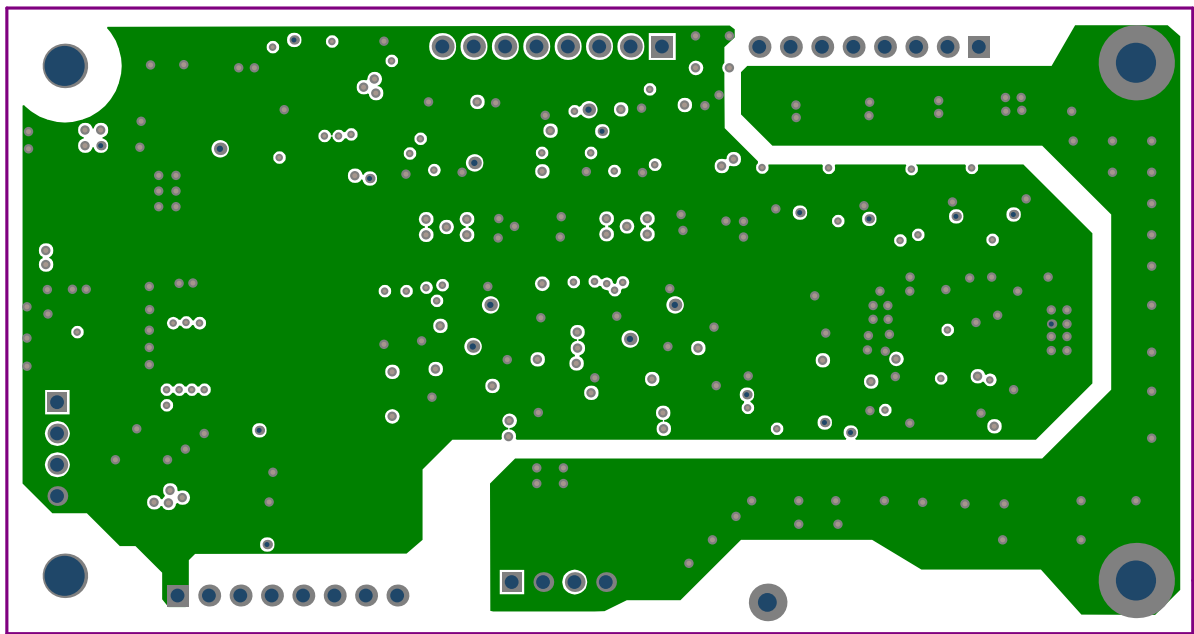


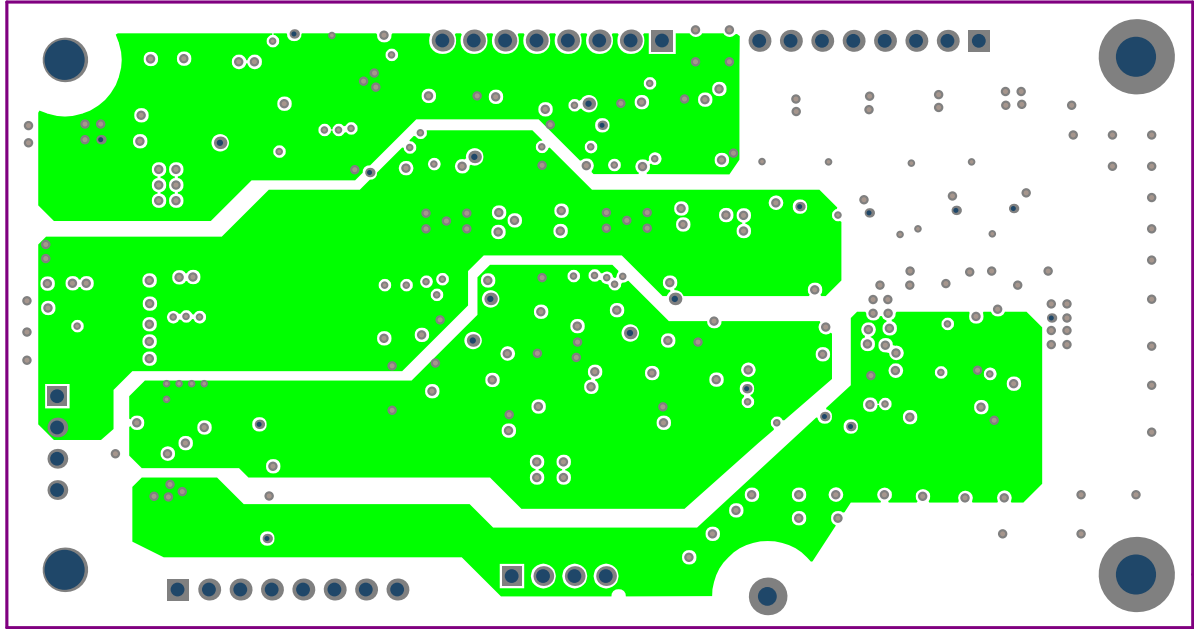
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	



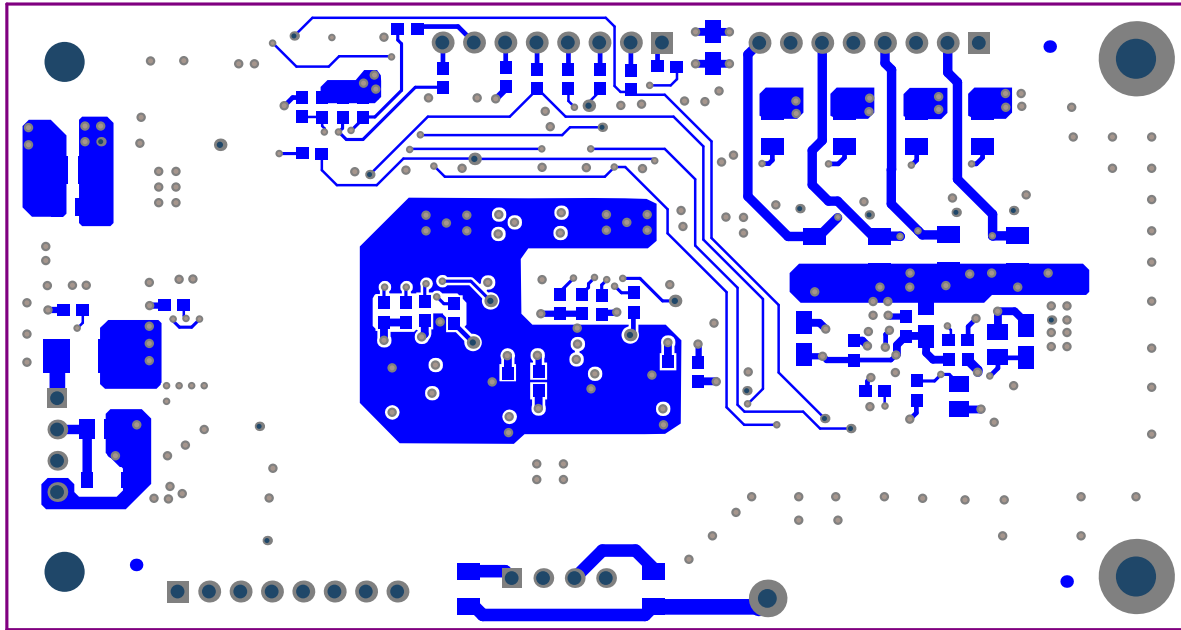
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	



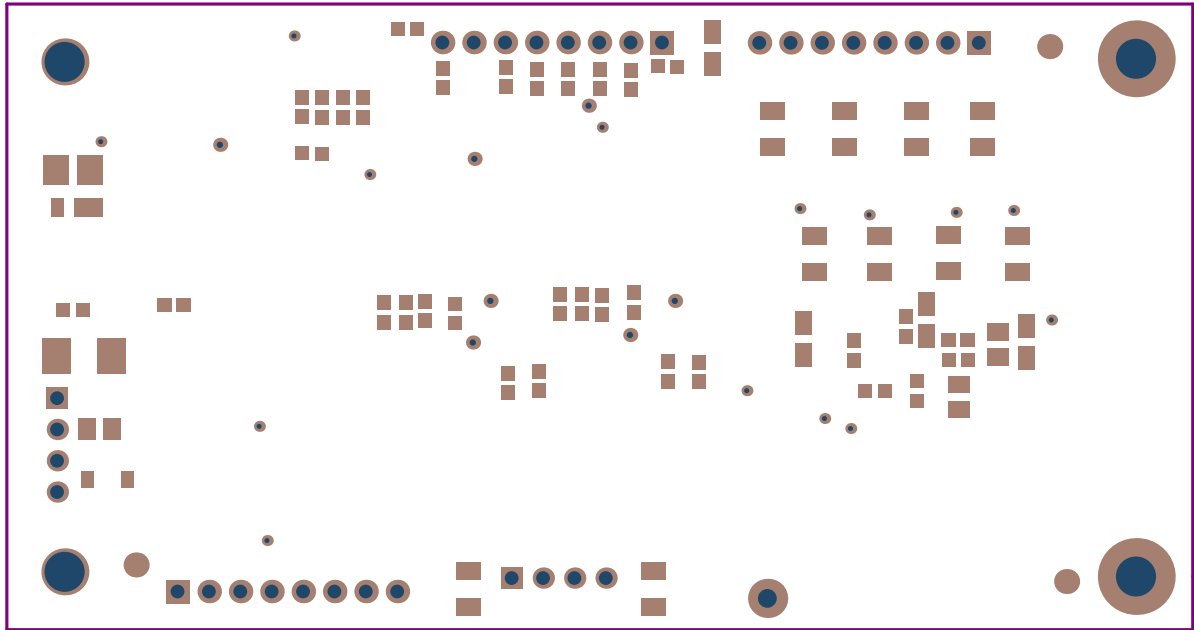
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = L2_GND-PLANE			
PLOT NAME = MidLayer1	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	



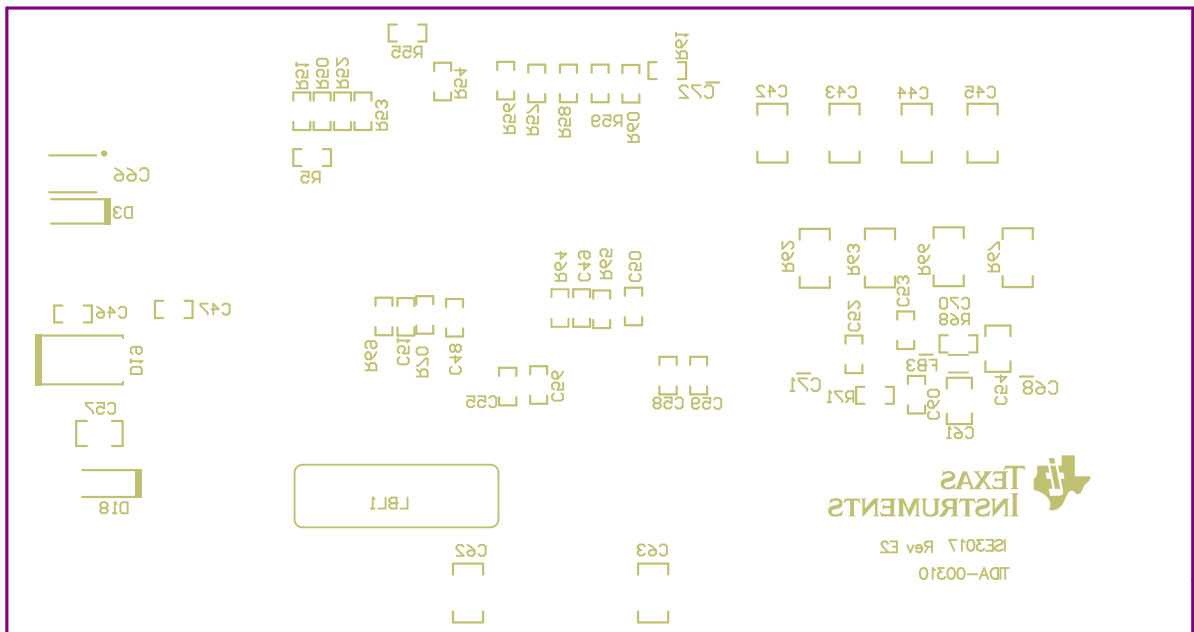
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = L3_PWR-PLANE			
PLOT NAME = MidLayer2	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:ISE3017	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = MI Board Outline			
PLOT NAME = Board Outline	GENERATED : 10/1/2014 11:45:10 AM	TEXAS INSTRUMENTS	

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